



## SUNLU Filaments Parameters

Material	Printing Temp. (°C)	Platform Temp. (°C)	Bedding plate (°C)	Thermal Deformation Temp. (°C)	Melt Mass Flow Rate	Density (g/cm³)	Tensile Strength (MPa)	Resilience Elongation (%)	Water Absorption (%)	Tolerance
PLA	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	25g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PLA+	210-235	70-100°C	100-100	57	9-11g/10min (90°C, 2.18kg)	1.24	11-12	45	0.50%	±0.02mm
PLA Red wood	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	25g/10min (100°C, 2.18kg)	1.24	11-12	4	0.50%	±0.02mm
PA6	200-240	1. No need when with glue stick 2. 60-80°C without glue stick	140-140	54	11-13g/10min (100°C, 2.18kg)	1.14	8-9	110	0.10%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	55	20-21g/10min (100°C, 2.18kg)	1.24	11-12	4	0.70%	±0.02mm
ABS	240-260	Get metal cooling with Infrared insulation and semi sealed?	120-120	44	10-11g/10min (220°C, 1.98kg)	1.18	4-11	44	1.10%	±0.02mm
ABS High Temp.	250-270	Get metal cooling with Infrared insulation and semi sealed?	150-150	39	10-11g/10min (220°C, 1.98kg)	1.17	6-13	20	1.10%	±0.02mm
ABS Resistant	250-270	Get metal cooling with Infrared insulation and semi sealed?	170-180	37	10-11g/10min (220°C, 1.98kg)	1.18	6-11	19	1.10%	±0.02mm
HDPE	200-220	30-100°C	100-100	31	10-11g/10min (200°C, 1.94kg)	1.11	5-7	31	1.30%	±0.02mm
PC/PC	200-230	1. No need when with glue stick 2. 70-80°C without glue stick	100-100	55	6-11g/10min (200°C, 2.16kg)	1.28	6-4	210	0.30%	±0.02mm
WASA	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	41	8-11g/10min (90°C, 2.16kg)	1.33	6-13	4	1.70%	±0.02mm
TPU	200-230	No need	100-100	4	10-11g/10min (100°C, 2.16kg)	1.21	7	600	0.70%	±0.02mm
PA	240-260	30-100°C	120-120	58	34g/10min (200°C, 2.18kg)	1.13	5-7	200	0.60%	±0.02mm
PE	200-230	Get metal cooling with Infrared insulation and semi sealed?	200-240	39	20-25g/10min (220°C, 2.18kg)	1.2	5-6	110	0.30%	±0.02mm
ASA	240-260	1. No need when with glue stick 2. 60-80°C without glue stick	140-140	4	14-15g/10min (100°C, 2.18kg)	1.24	9-11	30-4	0.10%	±0.02mm
PC	20-100	No need	50-50	4	10-11g/10min (100°C, 2.18kg)	1.21	7	300	0.70%	±0.02mm
PLA9A	200-240	30-100°C	150-150	52	9-11g/10min (220°C, 2.18kg)	1.19	6-12	12	0.60%	±0.02mm
ASA	250-280	30-100°C	170-180	38	9-11g/10min (220°C, 1.98kg)	1.24	6-10	24	1.30%	±0.02mm
PLA Carbon Fiber	200-230	1. No need when with glue stick 2. 60-80°C without glue stick	100-100	52	11-16g/10min (220°C, 2.18kg)	1.2	11-11	3	0.50%	±0.02mm